Claims

1. A curable resin composition, comprising a curable resin component, triphenylphosphine oxide, and a filler, the triphenylphosphine oxide being included in the curable resin composition in an amount of 1.1% by mass or more.

2. The curable resin composition according to claim 1, wherein the triphenylphosphine oxide is included in the curable resin composition in an amount of 6.0% by mass or less.

3. The curable resin composition according to claim 1, wherein the triphenylphosphine oxide is included in the curable resin composition in an amount of 3.0% by mass or less.

4. The curable resin composition according to any one of claim 1 to claim 3, wherein the curable resin component includes an epoxy resin and a curing agent.

5. The curable resin composition according to any one of claim 1 to claim 4, which is a sealing material for an electronic component device.

6. The curable resin composition according to any one of claim 1 to claim 5, which is a sealing material for producing at least one package of an electronic component device that includes two or more packages.

7. An electronic component device, comprising a package that includes a cured product of the curable resin composition according to any one of claim 1 to claim 6.

8. The electronic component device according to claim 7, comprising a first package and a second package, the first package including a cured product of the curable resin composition according to any one of claim 1 to claim 6.

9. A method of producing an electronic component device, comprising bonding together a first package and a second package, the first package including a cured product of the curable resin composition according to any one of claim 1 to claim 6, the bonding being carried out such that a state of warping of the first package is in accordance with a state of warping of the second package.